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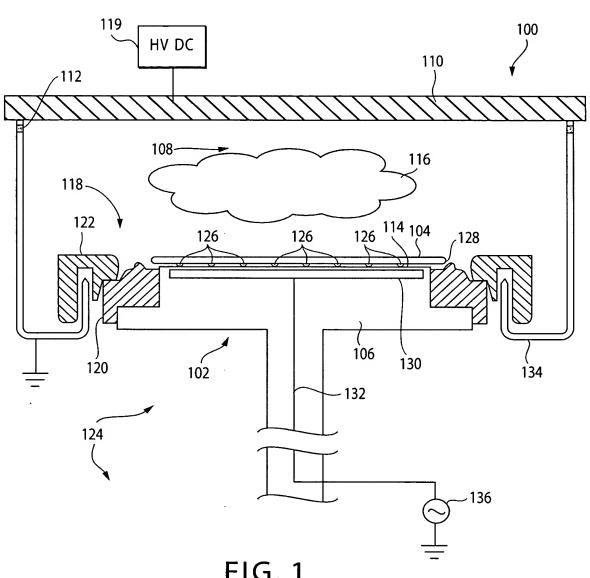
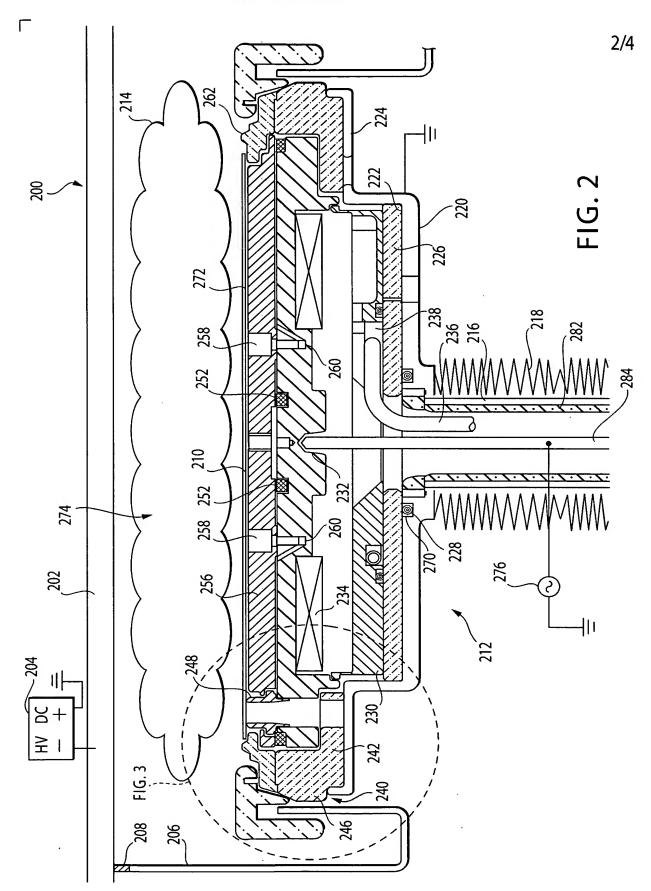


FIG. 1 PRIOR ART

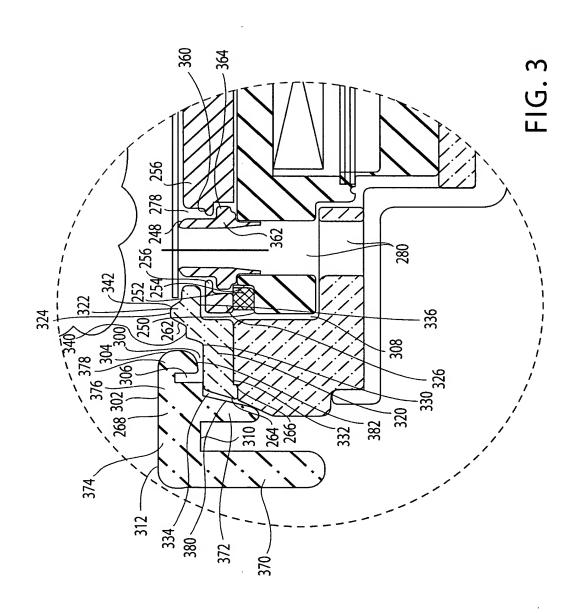
Sheet 2 of 4
Applicant: Stimson, et al.
Title: PROCESS KIT FOR IMPROVED POWER
COUPLING THROUGH A WORKPIECE IN A
SEMICONDUCTOR WAFER PRPOCESSING
SYSTEM
Docket: 1946C2/AGS/IBSS/LP



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Sheet 3 of 4
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Applicant: Stimson, et al.
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